

Electrical Characteristics

at $T_{\rm j}$ = 25 °C, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain-source breakdown voltage $V_{\rm GS}$ = 0, $I_{\rm D}$ = 0.25 mA	$V_{(BR)DSS}$	60	_	_	V
Gate threshold voltage $V_{\rm GS}$ = $V_{\rm DS}$, $I_{\rm D}$ = 1.0 mA	$V_{GS(th)}$	2.5	3.0	3.5	
Zero gate voltage drain current $V_{\rm GS}$ = 60 V, $V_{\rm DS}$ = 0 $T_{\rm j}$ = 25 °C $T_{\rm color}$	$I_{ extsf{DSS}}$	_	0.1	1.0	μΑ
$T_{ m j}$ = 150 °C Gate-source leakage current $V_{ m GS}$ = \pm 20 V, $V_{ m DS}$ = 0 $T_{ m j}$ = 25 °C	I_{GSS}		10	100	nA
$T_{\rm j}$ = 150 °C Drain-source on-state resistance	$R_{ extsf{DS(on)}}$	_	0.12	0.15	μΑ
$V_{\rm GS}$ = 10 V, $I_{\rm D}$ = 7.5 A Dynamic Characteristics					
Forward transconductance $V_{\rm DS} \ge 2 \times I_{\rm D} \times R_{\rm DS(on)max}, I_{\rm D} = 7.5 \ {\rm A}$	g_{fs}	3.0	5.7	_	S
Input capacitance $V_{\rm GS}$ = 0, $V_{\rm DS}$ = 25 V, f = 1 MHz	C_{iss}	_	360	480	pF
Output capacitance $V_{\rm GS}$ = 0, $V_{\rm DS}$ = 25 V, f = 1 MHz	C_{oss}	_	160	250	
Reverse transfer capacitance $V_{\rm GS}$ = 0, $V_{\rm DS}$ = 25 V, f = 1 MHz	C_{rss}	_	50	90	
Turn-on time $t_{\rm on}$, $(t_{\rm on}=t_{\rm d(on)}+t_{\rm r})$ $V_{\rm CC}$ = 30 V, $V_{\rm GS}$ = 10 V, $I_{\rm D}$ = 3 A, $R_{\rm GS}$ = 50 Ω	t _{d(on)}		15 30	25 45	ns
Turn-off time $t_{\rm off}$, $(t_{\rm off}=t_{\rm d(off)}+t_{\rm f})$ $V_{\rm CC}=$ 30 V, $V_{\rm GS}=$ 10 V, $I_{\rm D}=$ 3 A, $R_{\rm GS}=$ 50 Ω	$t_{\sf d(off)}$	_	40 55	55 75	



Electrical Characteristics (cont'd)

at T_i = 25 °C, unless otherwise specified.

Parameter	Symbol		Value	s	Unit
		min.	typ.	max.	
Reverse Diode					
Continuous source current	Is	_	_	12	Α
Pulsed source current	I_{SM}	_	_	48	
Diode forward on-voltage $I_{\rm F}$ = 12 A, $V_{\rm GS}$ = 0 V	V_{SD}	_	1.3	1.6	V
Reverse recovery time $I_F = I_S$, $di_F/dt = 100 \text{ A/}\mu\text{s}$, $V_R = 30 \text{ V}$	t _{rr}	_	60	_	ns
Reverse recovery charge $I_F = I_S$, $di_F/dt = 100$ A/ μ s, $V_R = 30$ V	Q_{rr}	_	0.1	_	μС
Temperature Sensor					
Forward voltage $I_{TS(on)} = 10$ mA, $T_j = -55$ + 150 °C Sensor override, $t_p \le 100$ μs	$V_{TS(on)}$	_	1.4	1.5	V
$T_{\rm j} = -55 \dots + 160 {\rm ^{\circ}C}$		_	_	10	
Forward current $T_{\rm j} = -55 \dots + 150 ^{\circ}{\rm C}$ Sensor override, $t_{\rm p} \le 100 \mu{\rm s}$	$I_{TS(on)}$	_	_	10	mA
$T_{\rm j} = -55 \dots + 160 {}^{\circ}{\rm C}$		_	_	600	
Holding current, $V_{\rm TS(off)}$ = 5.0 V, $T_{\rm j}$ = 25 °C $T_{\rm j}$ = 150 °C	I_{H}	0.05 0.05	0.1 0.2	0.5 0.3	
Switching temperature $V_{TS} = 5.0 \text{ V}$	$T_{TS(on)}$	150	_	_	°C
Turn-off time $V_{TS} = 5.0 \text{ V}, I_{TS(on)} = 2 \text{ mA}$	$t_{ m off}$	0.5	_	2.5	μs



Examples for short-circuit protection

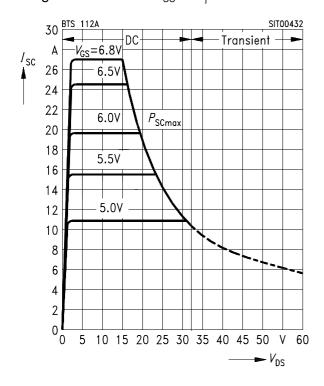
at $T_i = -55 \dots + 150 \,^{\circ}$ C, unless otherwise specified.

Parameter	Symbol	Examples			Unit
		1	2	_	
Drain-source voltage	$V_{ t DS}$	15	30	_	V
Gate-source voltage	V_{GS}	6.8	5.0	_	
Short-circuit current	$I_{ m SC}$	27	11	_	А
Short-circuit dissipation	P_{SC}	400	330	_	W
Response time $T_i = 25 ^{\circ}\text{C}$, before short circuit	$t_{ m SC(off)}$	20	20	_	ms

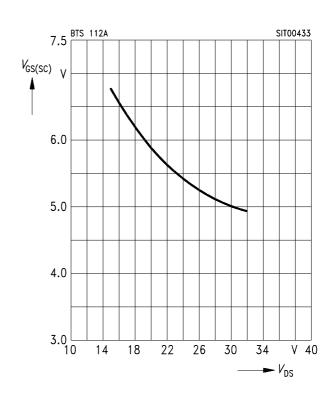
Short-circuit protection $I_{SC} = f(V_{DS})$

Parameter: V_{GS}

Diagram to determine I_{SC} for $T_i = -55... + 150$ °C

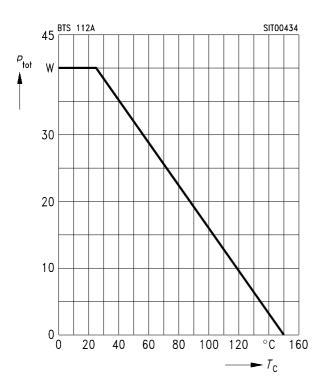


Max. gate voltage $V_{\rm GS(SC)}$ = f ($V_{\rm DS}$) Parameter: $T_{\rm j}$ = - 55 ... + 150 °C

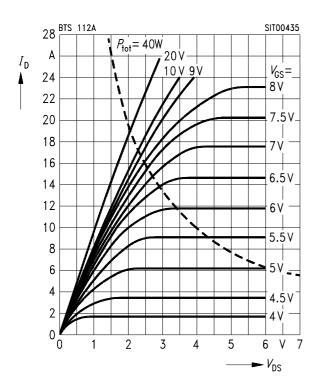




Max. power dissipation $P_{\text{tot}} = f(T_{\text{C}})$

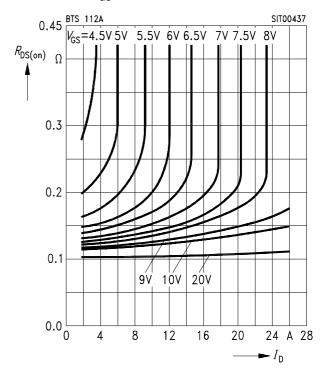


Typical output characteristics $I_{\rm D}$ = $f(V_{\rm DS})$ Parameter: $t_{\rm p}$ = 80 s

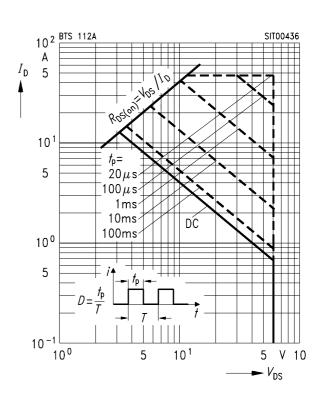


Typ. drain-source on-state resistance

 $R_{\mathrm{DS(on)}} = f(I_{\mathrm{D}})$ Parameter: V_{GS}



Safe operating area $I_D = f(V_{DS})$ Parameter: D = 0.01, $T_C = 25$ °C

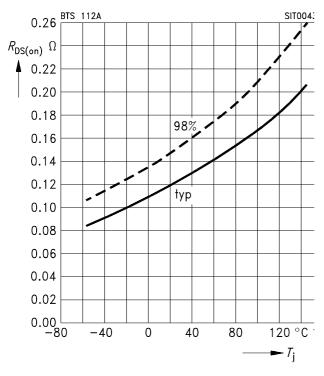




Drain-source on-state resistance

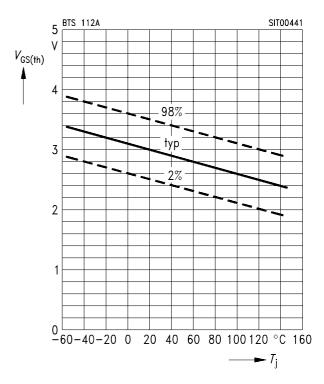
 $R_{\rm DS(on)} = f(T_{\rm i})$

Parameter: I_D = 5 A, V_{GS} = 10 V



Gate threshold voltage $V_{\mathrm{GS(th)}} = f\left(T_{\mathrm{j}}\right)$

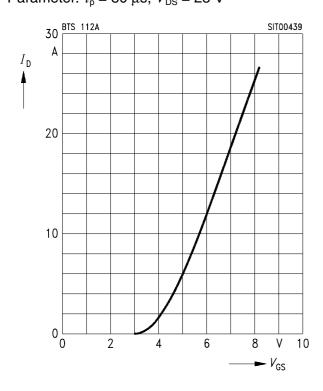
Parameter: $V_{DS} = V_{GS}$, $I_{D} = 1$ mA



Typ. transfer characteristic

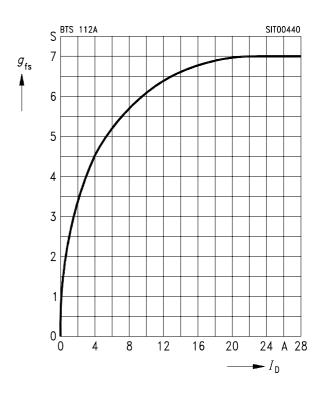
 $I_{\rm D} = f(V_{\rm GS})$

Parameter: $t_p = 80 \mu s$, $V_{DS} = 25 \text{ V}$



Typ. transconductance $g_{fs} = f(I_D)$

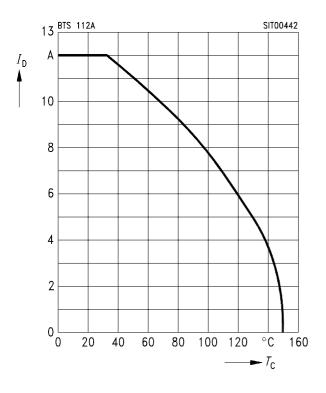
Parameter: $t_p = 80 \mu s$, $V_{DS} = 25 \text{ V}$





Continuous drain current $I_D = f(T_C)$

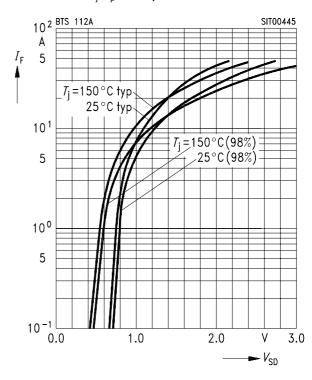
Parameter: $V_{\rm GS} \ge -10 \text{ V}$



Forward characteristics of reverse diode

 $I_{\mathsf{F}} = f(V_{\mathsf{SD}})$

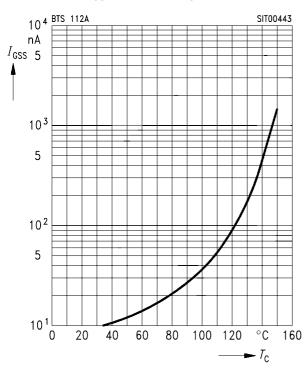
Parameter: $T_{\rm j}$, $t_{\rm p}$ = 80 μ s



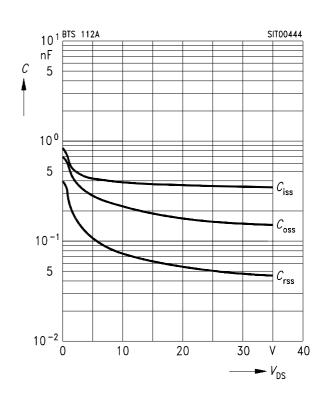
Typ. gate-source leakage current

 $I_{\text{GSS}} = f(T_{\text{C}})$

Parameter: $V_{GS} = -20 \text{ V}$, $V_{DS} = 0$



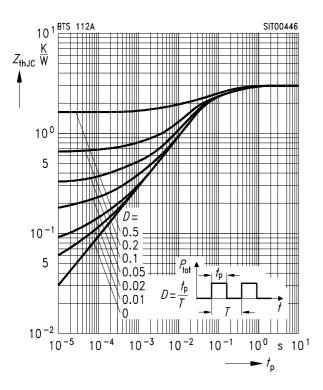
Typ. capacitances $C = f(V_{\rm DS})$ Parameter: $V_{\rm GS} = 0, f = 1 \ \rm MHz$





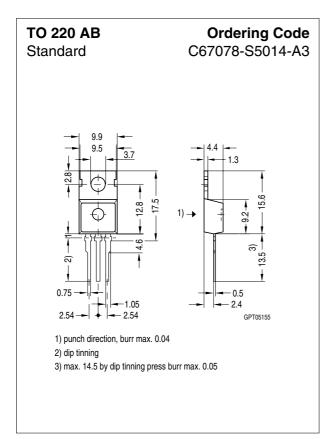
Transient thermal impedance $Z_{\text{thJC}} = f(t_{\text{p}})$

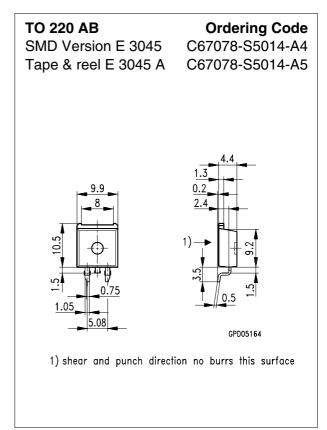
Parameter: $D = t_p/T$











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